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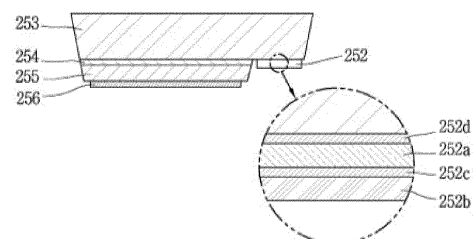
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(54) **DISPLAY DEVICE USING SEMICONDUCTOR LIGHT EMITTING ELEMENTS, AND METHOD FOR MANUFACTURING SAME**

(57) The present disclosure relates to a display device using semiconductor light emitting devices and a fabrication method thereof, and more particularly, a display device according to the present disclosure may include a semiconductor light emitting device, and a substrate having a receiving groove in which the semiconductor light emitting device is accommodated, wherein the semiconductor light emitting device includes a first conductive semiconductor layer, a second conductive semiconductor layer disposed at an upper portion of the first conductive semiconductor layer, a first conductive electrode disposed on the first conductive semiconductor layer, and a second conductive electrode disposed on the second conductive semiconductor layer, and spaced apart from the first conductive electrode along a horizontal direction, wherein when the semiconductor light emitting device is assembled into the receiving groove, the first conductive semiconductor layer has an asymmetrical shape with respect to at least one direction so that the first conductive electrode and the second conductive electrode are arranged at preset positions.

FIG. 4B



Description

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0001] The present disclosure relates to a display device and a fabrication method thereof, and more particularly, to a display device using a semiconductor light emitting device.

2. Description of the Conventional Art

[0002] In recent years, liquid crystal displays (LCDs), organic light emitting diode (OLED) displays, and micro LED displays have been competing to implement a large-area display in the field of display technology.

[0003] Meanwhile, when semiconductor light emitting devices (micro LED (μ LED)) having a diameter or a cross sectional area of 100 microns or less are used in a display, the display may provide a very high efficiency because it does not absorb light using a polarizing plate or the like. However, since a large-sized display requires millions of semiconductor light emitting devices, it has difficulty in transferring the devices compared to other technologies.

[0004] Technologies currently in development for transfer processes include pick & place, laser lift-off (LLO), self-assembly, or the like. Among them, the self-assembly method, which is a method in which the semiconductor light emitting device locates themselves in a fluid, is the most advantageous method for realizing a large-sized display device.

[0005] In recent years, U.S. Patent No. 9,825,202 proposed a micro LED structure suitable for self-assembly, but there is not yet research on technologies for fabricating a display through self-assembly of micro LEDs.

[0006] In addition, in order to transfer micro LEDs to fabricate a display, electrical connection (i.e. wiring) for applying a current or voltage to each of the micro LEDs may be required, and thus a new type of structure and fabrication method in consideration of the wiring in the self-assembly will be presented.

SUMMARY OF THE INVENTION

[0007] An object of the present disclosure is to provide a new fabrication process with high reliability in a large-screen display using micro-sized semiconductor light emitting devices.

[0008] Another object of the present disclosure is to provide a fabrication process and structure of a display capable of controlling an assembly direction when semiconductor light emitting devices are self-assembled on a wiring substrate.

[0009] A display device according to the present disclosure may have an asymmetrical shape between a receiving groove of a wiring substrate and a semiconductor

light emitting device, and an assembly direction may also be ensured while performing self-assembly with a horizontal chip using the asymmetrical shape, thereby simplifying the wiring process subsequent to the assembly.

[0010] More specifically, the display device may include a semiconductor light emitting device, and a substrate having a receiving groove in which the semiconductor light emitting device is accommodated, wherein the semiconductor light emitting device includes a first conductive semiconductor layer, a second conductive semiconductor layer disposed at an upper portion of the first conductive semiconductor layer, a first conductive electrode disposed on the first conductive semiconductor layer, and a second conductive electrode disposed on the second conductive semiconductor layer, and spaced apart from the first conductive electrode along a horizontal direction, and when the semiconductor light emitting device is assembled into the receiving groove, the first conductive semiconductor layer has an asymmetrical shape with respect to at least one direction so that the first conductive electrode and the second conductive electrode are arranged at preset positions.

[0011] According to an embodiment, the first conductive semiconductor layer may have a symmetrical shape with respect to the other direction perpendicular to the one direction. The first conductive electrode and the second conductive electrode may be arranged in a row along the other direction.

[0012] The cross section of the first conductive semiconductor layer may include a circular portion, and a straight portion connecting both ends of the circular portion. The center of the cross section of the first conductive semiconductor layer may be eccentrically formed on one side along the other direction.

[0013] According to an embodiment, the receiving groove may be formed in a passivation layer, and the receiving groove may have an asymmetrical shape with respect to the one direction so as to match the shape of the first conductive semiconductor layer.

[0014] The first conductive electrode and the second conductive electrode may be connected to a first wiring electrode and a second wiring electrode, respectively, and the first wiring electrode and the second wiring electrode may be extended to one surface of the passivation layer. The substrate may include a plurality of pair electrodes that generate an electric field when an electric current is supplied thereto. The first wiring electrode and the second wiring electrode may be formed on an opposite side to the plurality of the pair electrodes with respect to the semiconductor light emitting devices.

[0015] According to an embodiment, at least one of the first conductive electrode and the second conductive electrode may include a magnetic body.

[0016] In addition, the present disclosure may disclose a fabrication method of a display device, and the method may include transferring a substrate to an assembly position, and placing semiconductor light emitting devices having a first conductive semiconductor layer and a sec-

ond conductive semiconductor layer into a fluid chamber, guiding the movement of the semiconductor light emitting devices in the fluid chamber to assemble the semiconductor light emitting devices into receiving grooves of the substrate, and connecting a first wiring electrode and a second wiring electrode to the plurality of semiconductor light emitting devices, wherein at least one of the plurality of conductive semiconductor layers of the plurality of semiconductor light emitting devices has an asymmetrical shape with respect to one direction so that the conductive electrodes of the semiconductor light emitting devices are arranged at preset positions when the semiconductor light emitting devices are assembled into the receiving grooves.

[0017] According to an embodiment, said assembly process may include applying a magnetic field to the semiconductor light emitting devices to move the semiconductor light emitting devices along a magnetic force in the fluid chamber, and guiding the semiconductor light emitting devices to the receiving grooves of the substrate by applying an electric field so that the semiconductor light emitting devices are placed at the receiving grooves during the movement of the semiconductor light emitting devices.

[0018] According to the present disclosure having the foregoing configuration, a large number of semiconductor light emitting devices may be assembled at one time in a display device in which individual pixels are formed with micro light emitting diodes. In addition, according to the present disclosure, an assembly direction of a horizontal semiconductor light emitting device may be ensured by performing self-assembly using the asymmetrical shape between a receiving groove and a semiconductor light emitting device, thereby having an advantage capable of simplifying the wiring process subsequent to the assembly.

[0019] As described above, according to the present disclosure, a large number of semiconductor light emitting devices may be pixelated on a wafer having a small size, and then directly transferred onto a large-area substrate. Furthermore, as the wiring of the semiconductor light emitting devices is carried out on a substrate, it is possible to directly transfer the semiconductor light emitting devices to a wiring substrate without using a temporary substrate. Through this, it may be possible to fabricate a large-area display device at a low cost.

[0020] In addition, according to the fabrication method and device of the present disclosure, semiconductor light emitting devices may be simultaneously transferred to exact positions using a magnetic field and an electric field in a solution, thereby allowing a low cost, high efficiency, and high-speed transfer implementation.

[0021] In addition, since assembly by an electric field is carried out, selective assembly is allowed through a selective electrical application without any additional device or process. Accordingly, red, green, and blue micro LEDs may be selectively assembled at desired positions.

BRIEF DESCRIPTION OF THE DRAWING

[0022] The accompanying drawings, which are included to provide a further understanding of the invention and are incorporated in and constitute a part of this specification, illustrate embodiments of the invention and together with the description serve to explain the principles of the invention. In the drawings:

FIG 1 is a conceptual view illustrating a display device using a semiconductor light emitting device according to an embodiment of the present disclosure. FIG. 2 is a partially enlarged view showing a portion "A" of the display device in FIG. 1.

FIG. 3 is an enlarged view showing a semiconductor light emitting device in FIG. 2.

FIGS. 4A and 4B are a plan view and a cross-sectional view showing another embodiment of the semiconductor light in FIG. 2.

FIGS. 5A through 5E are conceptual views for explaining a new process of fabricating the foregoing semiconductor light emitting device.

FIG. 6 is a conceptual view showing an example of a self-assembly device of semiconductor light emitting devices according to the present disclosure.

FIG. 7 is a block diagram showing the self-assembly device in FIG. 6.

FIGS. 8A through 8G are conceptual views showing a process of self-assembling semiconductor light emitting devices using the self-assembly device in FIG. 6.

FIGS. 9A through 9D are conceptual views showing a process of fabricating a display device after self-assembling semiconductor light emitting devices on a wiring substrate using the self-assembly device in FIG. 6.

FIGS. 10A through 10D are plan views showing a modified example of the semiconductor light emitting device of the present disclosure.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

[0023] Hereinafter, the embodiments disclosed herein will be described in detail with reference to the accompanying drawings, and the same or similar elements are designated with the same numeral references regardless of the numerals in the drawings and their redundant description will be omitted. A suffix "module" and "unit" used for constituent elements disclosed in the following description is merely intended for easy description of the specification, and the suffix itself does not give any special meaning or function. In describing the present disclosure, if a detailed explanation for a related known function or construction is considered to unnecessarily divert the gist of the present disclosure, such explanation has been omitted but would be understood by those skilled in the art. Also, it should be noted that the accompanying

drawings are merely illustrated to easily explain the concept of the invention, and therefore, they should not be construed to limit the technological concept disclosed herein by the accompanying drawings.

[0024] Furthermore, it will be understood that when an element such as a layer, region or substrate is referred to as being "on" another element, it can be directly on the another element or an intermediate element may also be interposed therebetween.

[0025] A display device disclosed herein may include a portable phone, a smart phone, a laptop computer, a digital broadcast terminal, a personal digital assistant (PDA), a portable multimedia player (PMP), a navigation, a slate PC, a tablet PC, an ultrabook, a digital TV, a digital signage, a head-mounted display (HMD), a desktop computer, and the like. However, it would be easily understood by those skilled in the art that a configuration disclosed herein may be applicable to any displayable device even though it is a new product type which will be developed later.

[0026] FIG. 1 is a conceptual view illustrating a display device using a semiconductor light emitting device according to an embodiment of the present disclosure, and FIG. 2 is a partially enlarged view showing a portion "A" of the display device in FIG. 1, and FIG. 3 is an enlarged view showing a semiconductor light emitting device in FIG. 2, and FIGS. 4A and 4B are a plan view and a cross-sectional view showing another embodiment of the semiconductor light in FIG. 2.

[0027] According to the illustration, information processed in the controller of the display device 100 may be displayed on a display module 140. A case 101 in the form of a closed loop surrounding an edge of the display module may form a bezel of the display device.

[0028] The display module 140 may include a panel 141 on which an image is displayed, and the panel 141 may include micro-sized semiconductor light emitting devices 150 and a wiring substrate 110 on which the semiconductor light emitting devices 150 are mounted.

[0029] Wiring lines may be formed on the wiring substrate 110, and connected to an n-type electrode 152 and a p-type electrode 156 of the semiconductor light emitting device 150. Through this, the semiconductor light emitting device 150 may be provided on the wiring substrate 110 as a self-emitting individual pixel.

[0030] An image displayed on the panel 141 is visual information, and implemented by independently controlling the light emission of a sub-pixel arranged in a matrix form through the wiring lines.

[0031] According to the present invention, a micro LED (Light Emitting Diode) is illustrated as one type of the semiconductor light emitting device 150 that converts current into light. The micro LED may be a light emitting diode formed with a small size of 100 microns or less. The semiconductor light emitting device 150 may be provided in blue, red, and green light emitting regions, respectively, to implement a sub-pixel by a combination of the light emitting regions. In other words, the sub-pixel

denotes a minimum unit for implementing a single color, and at least three micro LEDs may be provided in the sub-pixel.

[0032] More specifically, referring to FIG. 3, the semiconductor light emitting device 150 may be a vertical structure.

[0033] For example, the semiconductor light emitting devices 150 may be implemented with a high-power light emitting device that emits various lights including blue in which gallium nitride (GaN) is mostly used, and indium (In) and/or aluminum (Al) are added thereto.

[0034] The vertical semiconductor light emitting device may include a p-type electrode 156, a p-type semiconductor layer 155 formed with the p-type electrode 156, an active layer 154 formed on the p-type semiconductor layer 155, an n-type semiconductor layer 153 formed on the active layer 154, and an n-type electrode 152 formed on the n-type semiconductor layer 153. In this case, the p-type electrode 156 located at the bottom may be electrically connected to a p-electrode of the wiring substrate, and the n-type electrode 152 located at the top may be electrically connected to an n-electrode at an upper side of the semiconductor light emitting device. The electrodes may be disposed in the upward/downward direction in the vertical semiconductor light emitting device 150, thereby providing a great advantage capable of reducing the chip size.

[0035] For another example, referring to FIGS. 4A and 4B, the semiconductor light emitting device may be a flip chip type semiconductor light emitting device.

[0036] For such an example, the semiconductor light emitting device 250 may include a p-type electrode 256, a p-type semiconductor layer 255 formed with the p-type electrode 256, an active layer 254 formed on the p-type semiconductor layer 255, an n-type semiconductor layer 253 formed on the active layer 254, and an n-type electrode 252 disposed to be separated from the p-type electrode 256 in the horizontal direction on the n-type semiconductor layer 253. In this case, both the p-type electrode 256 and the n-type electrode 252 may be electrically connected to the p-electrode and the n-electrode of the wiring substrate at the bottom of the semiconductor light emitting device.

[0037] Here, the n-type semiconductor layer 253 and the n-type electrode 252 may be defined as a first conductive semiconductor layer and a first conductive electrode, and the p-type electrode 256 and the p-type semiconductor layer 255 may be defined as a second conductive electrode and a second conductive semiconductor layer. However, the present disclosure is not necessarily limited thereto, and the n-type may be defined as a second conductive type, and the p-type may be defined as a first conductive type.

[0038] The vertical semiconductor light emitting device and the horizontal semiconductor light emitting device may be a green semiconductor light emitting device, a blue semiconductor light emitting device, or a red semiconductor light emitting device, respectively. The green

semiconductor light emitting device and the blue semiconductor light emitting device may be mostly formed of gallium nitride (GaN), and indium (In) and/or aluminum (Al) may be added thereto to implement a high-power light emitting device that emits green or blue light. For such an example, the semiconductor light emitting device may be a gallium nitride thin-film formed in various layers such as n-GaN, p-GaN, AlGaN, and InGa, and specifically, the p-type semiconductor layer may be p-type GaN, and the n-type semiconductor layer may be N-type GaN. However, in case of the red semiconductor light emitting device, the p-type semiconductor layer may be p-type GaAs and the n-type semiconductor layer may be n-type GaAs.

[0039] In addition, a p-electrode side in the p-type semiconductor layer may be p-type GaN doped with Mg, and an n-electrode side in the n-type semiconductor layer may be n-type GaN doped with Si. In this case, the above-described semiconductor light emitting devices may be semiconductor light emitting devices without an active layer.

[0040] On the other hand, referring to FIGS. 1 through 4, since the light emitting diode is very small, the display panel may be arranged with self-emitting sub-pixels arranged at fine pitch, thereby implementing a high-quality display device.

[0041] In a display device using the semiconductor light emitting device of the present disclosure described above, a semiconductor light emitting device grown on a wafer and formed through mesa and isolation is used as an individual pixel. In this case, the micro-sized semiconductor light emitting device 150 must be transferred to a wafer at a predetermined position on the substrate of the display panel. Pick and place is used for the transfer technology, but the success rate is low and a lot of time is required. For another example, there is a technology of transferring a plurality of devices at one time using a stamp or a roll, but the yield is limited and not suitable for a large screen display. The present disclosure proposes self-assembly using a fluid as a new fabrication method of a display device capable of solving the foregoing problems and a fabrication device using the same.

[0042] To this end, hereinafter, a new structure of the flip chip type semiconductor light emitting device will be described.

[0043] The semiconductor light emitting device of the present disclosure has a structure of an asymmetric micro LED. Specifically, when the semiconductor light emitting device is assembled into a receiving groove of the wiring substrate, the first conductive semiconductor layer may have an asymmetrical shape such that the first conductive electrode and the second conductive electrode are arranged at preset positions. In addition, the first conductive semiconductor layer may have a symmetrical shape with respect to the other direction perpendicular to the one direction.

[0044] For example, the n-type semiconductor layer 253 may have an asymmetric shape and the p-type sem-

iconductor layer 255 may have a symmetrical shape. Specifically, the cross section of the n-type semiconductor layer 253 may have a circular portion 253a and a straight portion 253b. The n-type semiconductor layer 253 may have a cylindrical shape in which part of the side surface is cut, and may have a shape in which the straight portion 253b connects both ends of the circular portion 253a when viewed from above. On the other hand, the p-type semiconductor layer 255 may have a structure in which the straight portion is disposed further inside. For another example, the p-type semiconductor layer 255 may have a circular or elliptical cross section.

[0045] In this case, the other direction may be a direction along a central axis (A1) perpendicular to the center of the straight portion 253b, and the one direction may be a direction in parallel to the straight portion 253b passing through the center of the circle. At this time, the first conductive electrode and the second conductive electrode are arranged in a row along the other direction. Specifically, the first conductive electrode and the second conductive electrode may be arranged in a row along a direction perpendicular to the straight portion 253b.

[0046] The shape of the receiving groove 290 of the wiring substrate 261 may be set so as to match the shape of the n-type semiconductor layer 253 since a portion having the largest area in the semiconductor light emitting device is the n-type semiconductor layer 253. Therefore, the receiving groove 290 of the wiring substrate 261 may include a circular portion 290a and a straight portion 290b (refer to FIG. 6), and both ends of the circular portion 290a is connected to the straight portion 290b.

[0047] According to such a structure of the semiconductor light emitting device, when the semiconductor light emitting device is assembled into the receiving groove 290, a relative position between the first conductive electrode and the second conductive electrode may be always constant. Therefore, the straight portion of the semiconductor light emitting device may be an assembly guide.

[0048] At least one of the first conductive electrode and the second conductive electrode may include a magnetic body. Using such a magnetic body, a magnetic force may be used in the self-assembly which will be described later.

[0049] For a specific example, the n-type electrode 252 may include the magnetic body. However, the present disclosure is not limited thereto, and the p-type electrode 256 may also include the magnetic substance. Here, the magnetic body may refer to a metal having magnetism. The magnetic body may be Ni, SmCo or the like, and for another example, a material corresponding to at least one of Gd-based, La-based, and Mn-based materials.

[0050] The magnetic body may be provided in the n-type electrode 252 in the form of particles. Furthermore, alternatively, for a conductive electrode including a magnetic body, a single layer of the conductive electrode may be made of a magnetic body. For an example of this, as illustrated in FIG. 9, the n-type electrode 252 of the semiconductor light emitting device may include a first layer

252a and a second layer 252b. Here, the first layer 252a may be made to include a magnetic material, and the second layer 252b may include a metal material other than the magnetic material. In this case, a buffer metal 252c may be disposed between the first layer 252a and the second layer 252b for coupling of different metal materials.

[0051] Furthermore, in the present example, another buffer metal 252d may be disposed between the first layer 252a including the magnetic body and the n-type semiconductor layer 253. However, the present disclosure is not necessarily limited thereto, and for another example, the first layer 252a may be disposed so as to be in contact with the n-type semiconductor layer 253 without the buffer metal 252d.

[0052] In this case, the first layer 252a is disposed between the second layer 252b and the second conductive semiconductor layer 253. The second layer 252b may be a contact metal connected to the second electrode of the wiring substrate.

[0053] Since the semiconductor light emitting device having the above structure is a horizontal type, the n and p wirings may be simultaneously carried out, and thus cost and time may be saved in fabricating the display device. In this case, it may be possible to transfer directly to a display panel other than a donor, thereby maximizing the transfer yield. In the present disclosure, a new fabrication method and fabrication device is presented to exert such effects using the structure of such a semiconductor light emitting device.

[0054] Hereinafter, a new fabrication method of the display device will be described. FIGS. 5A through 5E are conceptual views for explaining a new process of fabricating the foregoing semiconductor light emitting device.

[0055] In this specification, a display device using a passive matrix (PM) semiconductor light emitting device is illustrated. However, an example described below may also be applicable to an active matrix (AM) type semiconductor light emitting device. In addition, a method using a horizontal semiconductor light emitting device is illustrated, but it is also applicable to a method of self-assembling a vertical semiconductor light emitting device.

[0056] First, according to a manufacturing method, a first conductive semiconductor layer 253, an active layer 254, and a second conductive semiconductor layer 255 are respectively grown on a growth substrate 259.

[0057] When the first conductive semiconductor layer 253 is grown, next, the active layer 254 is grown on the first conductive semiconductor layer 253, and then the second conductive semiconductor layer 255 is grown on the active layer 1154. As described above, when the first conductive semiconductor layer 253, the active layer 254 and the second conductive semiconductor layer 255 are sequentially grown, the first conductive semiconductor layer 253, the active layer 254, and the second conductive semiconductor layer 255 form a layer structure as illustrated in FIG. 5A.

[0058] In this case, the first conductive semiconductor layer 253 may be an n-type semiconductor layer, and the second conductive semiconductor layer 255 may be a p-type semiconductor layer. However, the present disclosure is not limited thereto, and the first conductive type may be p-type and the second conductive type may be n-type.

[0059] In addition, the present embodiment illustrates a case where the active layer is present, but it is also possible to adopt a structure in which the active layer is not present as described above. For such an example, the p-type semiconductor layer may be p-type GaN doped with Mg, and an n-electrode side in the n-type semiconductor layer may be n-type GaN doped with Si.

[0060] The growth substrate 259 (wafer) may be formed of any one of materials having light transmission properties, for example, sapphire (Al_2O_3), GaN, ZnO, and AlO, but is not limited thereto. Furthermore, the growth substrate 259 may be formed of a carrier wafer, which is a material suitable for semiconductor material growth. The growth substrate (W) may be formed of a material having an excellent thermal conductivity, and for example, a SiC substrate having a higher thermal conductivity than a sapphire (Al_2O_3) substrate or a SiC substrate including at least one of Si, GaAs, GaP, InP and Ga_2O_3 may be used.

[0061] In this specification, a display device using a passive matrix (PM) semiconductor light emitting device is illustrated.

[0062] More specifically, isolation and mesa are carried out so that a plurality of light emitting elements form an array. In other words, the first conductive semiconductor layer 253, the active layer 254, and the second conductive semiconductor layer 255 are etched in a vertical direction to form a plurality of semiconductor light emitting devices.

[0063] In order to form the horizontal semiconductor light emitting device at this stage, the active layer 254 and the second conductive semiconductor layer 255 may be partially removed in a vertical direction to perform a mesa process in which the first conductive semiconductor layer 253 is exposed to the outside, and then isolation in which the first conductive semiconductor layer is etched to form a plurality of semiconductor light emitting device arrays. In this case, the semiconductor light emitting device may be isolated to a circular size of 100 μm or less in diameter.

[0064] Next, a first conductive electrode 252 (or n-type electrode) is formed on one surface of the first conductive semiconductor layer 253, and a second conductive semiconductor layer 255 (or p-type electrode) is formed on one surface of the second conductive semiconductor layer 255.

[0065] The conductive electrodes may be formed by a deposition process such as sputtering, but the present disclosure is not necessarily limited thereto. However, when the first conductive semiconductor layer and the second conductive semiconductor layer are an n-type

semiconductor layer and a p-type semiconductor layer, respectively, the second conductive electrode 256 may also be an n-type electrode.

[0066] At this time, at least one of the first conductive electrode 252 and the second conductive electrode 256 may have a magnetic body 257. The magnetic body 257 may refer to a metal having a magnetic property formed on a chip. The magnetic body may be Ni, Sn, Fe, Co or the like, and for another example, a material corresponding to at least one of Gd-based, La-based, and Mn-based materials.

[0067] Then, the growth substrate 259 is removed to provide a plurality of semiconductor light emitting devices 250. For example, the growth substrate 259 may be removed using a laser lift-off (LLO) or chemical lift-off (CLO) method (FIG. 5D).

[0068] Then, the process of mounting the plurality of semiconductor light emitting devices 250 on the substrate in a chamber filled with a fluid (FIG. 5E).

[0069] For example, the semiconductor light emitting devices 250 and the substrate are placed in a chamber filled with a fluid, and the semiconductor light emitting devices 250 are assembled to the substrate by themselves using flow, gravity, surface tension, or the like.

[0070] In the present disclosure, the substrate may be a wiring substrate 261. In other words, the wiring substrate 261 is placed in the fluid chamber so that the semiconductor light emitting devices 250 are directly mounted on the wiring substrate 261.

[0071] Meanwhile, the self-assembly method described above must increase transfer yield when applied to the fabrication of a large-screen display. The present disclosure proposes a method and device for increasing transfer yield.

[0072] In this case, in a display device according to the present disclosure, a magnetic force is applied to the magnetic body in the semiconductor light emitting device to move the semiconductor light emitting device, and places the semiconductor light emitting device at preset positions using an electric field in the movement process. Hereinafter, such a transfer method and device will be described in more detail with reference to the accompanying drawings.

[0073] FIG. 6 is a conceptual view showing an example of a self-assembly device of semiconductor light emitting devices according to the present invention, and FIG. 7 is a block diagram showing the self-assembly device in FIG. 6. Furthermore, FIGS. 8A through 8G are conceptual views showing a process of self-assembling semiconductor light emitting devices using the self-assembly device in FIG. 6.

[0074] According to the illustration of FIGS. 6 and 7, a self-assembly device 160 of the present disclosure may include a fluid chamber 162, a magnet 163, and a location controller 164.

[0075] The fluid chamber 162 has a space for accommodating a plurality of semiconductor light emitting devices. The space may be filled with a fluid, and the fluid

may include water or the like as an assembly solution. Accordingly, the fluid chamber 162 may be a water tank, and may be configured with an open type. However, the present disclosure is not limited thereto, and the fluid chamber 162 may be a closed type in which the space is formed with a closed space.

[0076] The substrate 261 may be disposed on the fluid chamber 162 such that an assembly surface on which the semiconductor light emitting devices 250 are assembled faces downward. For example, the substrate 261 may be transferred to an assembly position by a transfer unit, and the transfer unit may include a stage 165 on which the substrate is mounted. The stage 165 is positioned by the controller, and the substrate 261 may be transferred to the assembly position through the stage 165.

[0077] At this time, the assembly surface of the substrate 261 faces the bottom of the fluid chamber 162 at the assembly position. According to the illustration, the assembly surface of the substrate 261 is disposed so as to be immersed in a fluid in the fluid chamber 162. Therefore, the semiconductor light emitting devices 250 are moved to the assembly surface in the fluid.

[0078] The substrate 261, which is an assembly substrate on which an electric field can be formed as well as a wiring substrate on which wiring lines are formed afterward, may include a base portion 261a, a dielectric layer 261b and a plurality of electrodes 261c, 261d.

[0079] The base portion 261a may be made of an insulating material, and the plurality of electrodes 261c may be a thin or a thick film bi-planar electrode patterned on one side of the base portion 261a. The electrode 261c may be formed of, for example, a laminate of Ti/Cu/Ti, an Ag paste, ITO, and the like.

[0080] More specifically, the electrode 261c may be a plurality of pair electrodes disposed on the substrate and provided with a first electrode and a second electrode that generate an electric field when an electric current is supplied.

[0081] The dielectric layer 261b is made of an inorganic material such as SiO₂, SiN_x, SiON, Al₂O₃, TiO₂, HfO₂, or the like. Alternatively, the dielectric layer 261b may be composed of a single layer or multiple layers as an organic insulator. A thickness of the dielectric layer 261b may be several tens of nanometers to several micrometers.

[0082] Furthermore, the wiring substrate 261 according to the present disclosure includes a plurality of receiving grooves 290 partitioned by partition walls.

[0083] For example, the wiring substrate 261 may be provided with receiving grooves 290 into which the semiconductor light emitting devices 250 are inserted so that the semiconductor light emitting devices 250 can easily be mounted on the wiring substrate 261. Specifically, receiving grooves 290 on which the semiconductor light emitting devices 250 are mounted are formed on the wiring substrate 261 at positions where the semiconductor light emitting devices 250 are aligned with the wiring elec-

trodes. The semiconductor light emitting devices 250 are assembled into the receiving grooves 290 while moving in the fluid.

[0084] The receiving grooves 290 may be sequentially arranged along one direction to constitute a cell. An inside of the receiving groove 290 may be a space defined by the partition wall 291. The shape of the groove may be the same as or similar to that of the semiconductor light emitting device. In other words, the receiving groove 290 may have an asymmetric shape to match the asymmetrical shape of the semiconductor light emitting device, as described above. Therefore, the receiving groove of the wiring substrate may include a circular portion 290a and a straight portion 290b, and both ends of the circular portion 290a are connected by the straight portion 290b.

[0085] The partition wall 291 constituting the receiving groove 290 is made to be shared with neighboring cells. In this case, the partition wall 291 may be made of a polymer material. Furthermore, the partition wall 291 may be protruded from the base portion 261a, and the receiving grooves 290 may be sequentially arranged along the one direction by the partition wall 291. More specifically, the receiving grooves 290 are sequentially arranged in row and column directions, and may have a matrix structure.

[0086] On the other hand, according to the present disclosure, a material same as that of the partition wall 291 may be filled inside the receiving groove 290 by a subsequent process. Accordingly, the partition wall 291 may be modified into a passivation layer surrounding the semiconductor light emitting devices. This will be described later.

[0087] On the other hand, a plurality of electrodes may be disposed on the substrate, and have a first electrode and a second electrode that generate an electric field when an electric current is supplied, and the first electrode and the second electrode may be referred to as a pair electrode 261c. In the present disclosure, a plurality of the pair electrodes 261c may be provided, and disposed at the bottom of each of the receiving grooves. The first electrode and the second electrode may be formed of electrode lines, and the plurality of electrode lines may be extended to neighboring cells.

[0088] The pair electrodes 261c are disposed below the receiving groove 290 and applied with different polarities to generate an electric field in the receiving groove 290. In order to form the electric field, the dielectric layer may cover the pair electrodes 261c, and the dielectric layer may form the bottom of the receiving groove 290. In such a structure, when different polarities are applied to the pair electrode 261c from a lower side of each receiving groove 290, an electric field may be formed, and the semiconductor light emitting device may be inserted into the receiving groove 290 by the electric field.

[0089] At the assembly position, the electrodes of the substrate 261 are electrically connected to the power supply unit 171. The power supply unit 171 applies power to the plurality of electrodes to generate the electric field.

[0090] According to the illustration, the self-assembly device may include a magnet 163 for applying a magnetic force to the semiconductor light emitting devices. The magnet 163 is spaced apart from the fluid chamber 162 to apply a magnetic force to the semiconductor light emitting devices 250. The magnet 163 may be disposed to face an opposite side of the assembly surface of the substrate 261, and the location of the magnet is controlled by the location controller 164 connected to the magnet 163. The semiconductor light emitting device 250 may have a magnetic body so as to move in the fluid by the magnetic field of the magnet 163.

[0091] Referring to FIGS. 6 and 7, more specifically, the self-assembly device may include a magnet handler that can be automatically or manually moved in the x, y, and z axes on the top of the fluid chamber or include a motor capable of rotating the magnet 163. The magnet handler and the motor may constitute the location controller 164. Through this, the magnet 163 rotates in a horizontal direction, a clockwise direction, or a counter-clockwise direction with respect to the substrate 261.

[0092] On the other hand, a light transmitting bottom plate 166 may be formed in the fluid chamber 162, and the semiconductor light emitting devices may be disposed between the bottom plate 166 and the substrate 161. An image sensor 167 may be positioned to view the bottom plate 166 so as to monitor an inside of the fluid chamber 162 through the bottom plate 166. The image sensor 167 is controlled by the controller 172, and may include an inverted type lens, a CCD, and the like to observe the assembly surface of the substrate 261.

[0093] The self-assembling apparatus described above is configured to use a combination of a magnetic field and an electric field, and using those fields, the semiconductor light emitting devices may be placed at preset positions of the substrate by an electric field in the process of being moved by a location change of the magnet. Such a new fabrication method may be a detailed example of the self-assembly method described above with reference to FIG. 5E. Hereinafter, an assembly process using the self-assembly device described above will be described in more detail.

[0094] First, a plurality of semiconductor light emitting devices 250 having magnetic bodies are formed through the process described with reference to FIGS. 5A through 5D. In this case, a magnetic body may be deposited on the semiconductor light emitting device in the process of forming the second conductive electrode in FIG. 5C.

[0095] Next, the substrate 261 is transferred to the assembly position, and the semiconductor light emitting devices 250 are put into the fluid chamber 162 (FIG. 8A).

[0096] As described above, the assembly position of the substrate 261 is a position at which the assembly surface on which the semiconductor light emitting devices 250 of the substrate 261 are assembled is disposed in a downward direction in the fluid chamber 162.

[0097] In this case, some of the semiconductor light emitting devices 250 may sink to the bottom of the fluid

chamber 162 and some may float in the fluid. When the light transmitting bottom plate 166 is provided in the fluid chamber 162, some of the semiconductor light-emitting devices 250 may sink to the bottom plate 166.

[0098] Next, a magnetic force is applied to the semiconductor light emitting devices 250 so that the semiconductor light emitting devices 250 float in the fluid chamber 162 in a vertical direction (FIG. 8B).

[0099] When the magnet 163 of the self-assembly device moves from its original position to an opposite side of the assembly surface of the substrate 261, the semiconductor light emitting devices 250 float in the fluid toward the substrate 261. The original position may be a position away from the fluid chamber 162. For another example, the magnet 163 may be composed of an electromagnet. In this case, electricity is supplied to the electromagnet to generate an initial magnetic force.

[0100] Meanwhile, in this example, a separation distance between the assembly surface of the substrate 261 and the semiconductor light emitting devices 250 may be controlled by adjusting the magnitude of the magnetic force. For example, the separation distance is controlled using the weight, buoyancy, and magnetic force of the semiconductor light emitting devices 250. The separation distance may be several millimeters to tens of micrometers from the outermost edge of the substrate.

[0101] Next, a magnetic force is applied to the semiconductor light emitting devices 250 so that the semiconductor light emitting devices 250 move in one direction in the fluid chamber 162. For example, the magnet 163 moves in a horizontal direction, a clockwise direction or a counterclockwise direction with respect to the substrate (FIG. 8C). In this case, the semiconductor light emitting devices 250 move in a direction parallel to the substrate 261 at a position spaced apart from the substrate 261 by the magnetic force.

[0102] Next, the process of applying an electric field to guide the semiconductor light emitting devices 250 to preset positions of the substrate 261 so as to allow the semiconductor light emitting devices 250 to be placed at the preset positions during the movement of the semiconductor light emitting devices 250 is carried out (FIG. 8D). The semiconductor light emitting devices 250 move in a direction perpendicular to the substrate 261 by the electric field to be placed on preset positions while moving along a direction parallel to the substrate 261.

[0103] The plurality of semiconductor light emitting devices are guided to preset positions of the substrate by an electric field and a magnetic field.

[0104] More specifically, electric power is supplied to a pair electrode, that is, a bi-planar electrode of the substrate 261 to generate an electric field, and assembly is carried out only at preset positions. In other words, the semiconductor light emitting devices 250 are assembled to the assembly position of the substrate 261 using a selectively generated electric field. For this purpose, the substrate 261 may include cells in which the semiconductor light emitting devices 250 are inserted.

[0105] At this time, the magnetic body 257 of the semiconductor light emitting devices 250 serves as a post for upper and lower division. Specifically, when a surface having the magnetic body 257 is inserted into the cell in a direction toward the pair electrode 261c, the semiconductor light emitting device is unable to be placed on the bottom of the cell (an outer surface of the dielectric layer) by the magnetic body 257.

[0106] On the other hand, the semiconductor light emitting devices 250 may be guided to the preset positions, then the magnet 163 may move in a direction away from the substrate 261 such that the semiconductor light emitting devices 250 remaining in the fluid chambers 162 fall to the bottom of the fluid chambers 162, (FIG. 8E). For another example, if power supply is stopped when the magnet 163 is an electromagnet, then the semiconductor light emitting devices 250 remaining in the fluid chamber 162 fall to the bottom of the fluid chamber 162.

[0107] Then, when the semiconductor light emitting devices 250 on the bottom of the fluid chamber 162 are collected, the collected semiconductor light emitting devices 250 may be reused.

[0108] When the display device of the present disclosure uses blue semiconductor light emitting devices, that is, when the semiconductor light emitting devices are all blue semiconductor light emitting devices, the blue semiconductor light emitting devices may be assembled into all the cells of the substrate.

[0109] On the other hand, according to this example, each of the red semiconductor light emitting device, the green semiconductor light emitting device, and the blue semiconductor light emitting device may be arranged at a desired position. If the foregoing semiconductor light emitting device 250 is a blue semiconductor light emitting device, the assembly process described with reference to FIGS. 8A through 8E may generate an electric field only in a cell corresponding to a blue pixel to assemble the blue semiconductor light emitting device at a corresponding position.

[0110] Then, the assembly process described with reference to 8A through 8E are carried out using the green semiconductor light emitting device 250a and the red semiconductor light emitting device 250b, respectively (FIGS. 8F and 8G). However, since the wiring substrate 261 is already loaded at the assembly position, the process of loading the substrate into the assembly position may be omitted.

[0111] Then, the process of unloading the wiring substrate 261 is carried out, and the assembly process is completed.

[0112] The above-described self-assembly device and method are characterized in that, in order to increase the assembly yield in a fluidic assembly, parts at a far distance are concentrated adjacent to a preset assembly site using a magnetic field, and a separate electric field is applied to the assembly site to selectively assemble the parts only in the assembly site. At this time, the assembly substrate is placed on an upper portion of the

water tank and the assembly surface faces downward, thereby preventing nonspecific coupling while minimizing the effect of gravity due to the weight of parts. In other words, in order to increase the transfer yield, the assembly substrate is placed on the top to minimize the effect of a gravitational or frictional force, and prevent nonspecific coupling.

[0113] Furthermore, the blue semiconductor light emitting device, the green semiconductor light emitting device, and the red semiconductor light emitting device may be assembled at desired positions, respectively.

[0114] As described above, according to the present disclosure having the foregoing configuration, a large number of semiconductor light emitting devices may be assembled at one time in a display device in which individual pixels are formed with semiconductor light emitting devices.

[0115] When the assembly process is completed as described above, a process of fabricating a display device may be carried out. Hereinafter, a fabrication process of such a display device will be described in detail with reference to the drawings.

[0116] FIGS. 9A through 9E are conceptual views showing a process of fabricating a display device after self-assembling semiconductor light emitting devices on a wiring substrate using the self-assembly device in FIG. 6.

[0117] The movement of the semiconductor light emitting devices in the fluid chamber are guided, and the semiconductor light emitting devices are assembled at preset positions of the substrate by the foregoing process, and then a passivation layer 270 is filled between the plurality of semiconductor light emitting devices while the semiconductor light emitting devices 250, 250a, 250b are assembled at the preset positions of the substrate 261 (FIGS. 9A and 9B).

[0118] More specifically, as described above, the wiring substrate 261 includes a plurality of receiving grooves 290 partitioned by partition walls, and a gap exists between the receiving groove 290 and the semiconductor light emitting device. The passivation layer 270 fills the gap while covering the semiconductor light emitting device together with the partition walls.

[0119] Through such a process, a structure in which the passivation layer 270 surrounds the semiconductor light emitting device may be formed on the display. In this case, the passivation layer 270 may be made of a polymer material so as to be integrated with the partition walls.

[0120] In the display device shown in FIG. 9D implemented by the above process, the passivation layer 270 may include a plurality of receiving grooves, and the plurality of semiconductor light emitting devices may be accommodated in the receiving grooves. In other words, the receiving grooves that have been provided in the self-assembly process in the final structure are changed into the internal spaces of the passivation layer 270.

[0121] Therefore, the receiving groove is formed in the

passivation layer, and has an asymmetrical shape with respect to one direction so as to match the shape of the first conductive semiconductor layer. Here, the one direction may be a direction parallel to the straight portion of the receiving groove, and along a central axis passing through the center of the circular portion.

[0122] In this case, an electric field generated by the pair electrodes 261c described with reference to FIG. 9D as described above may be formed inside the cells. In addition, the plurality of cells are arranged in a matrix structure, and the plurality of the pair electrodes 261c have a structure extended to neighboring cells.

[0123] Next, thereafter, a planarization process is carried out to planarize a top surface of the passivation layer 270, and contact holes 271, 272 for wiring lines may be formed.

[0124] The contact holes 271, 272 may be formed in the first conductive semiconductor layer 253 and the second conductive semiconductor layer 255, respectively.

[0125] Finally, the first wiring electrodes and the second wiring electrodes are connected to the plurality of semiconductor light emitting devices through the contact holes (FIG. 9D).

[0126] According to the illustration of FIG. 9D, the first wiring electrode 281 and the second wiring electrode 282 may be extended to one surface of the passivation layer 270. At this time, one surface of the passivation layer 270 may be a surface opposite to a surface covering the dielectric layer 261b. For example, the first wiring electrode 281 is extended to an upper surface of the passivation layer 270 on the first conductive semiconductor layer 253 through a first contact hole 271 formed on the first conductive semiconductor layer 253. The second wiring electrode 282 is extended to an upper surface of the passivation layer 270 through a second contact hole 272 formed on the second conductive semiconductor layer 255. However, for another example, when the second conductive electrode 256 (see FIG. 5D) is present on an upper surface of the second conductive semiconductor layer 255, the second wiring electrode 282 may be extended to an upper surface of the passivation layer 270 through the second contact hole 272.

[0127] According to such a structure, although transfer is carried out by self-assembly, the wiring lines of the flip-chip type semiconductor light emitting devices may be implemented. In this case, the passivation layer 270 may be disposed on a front side of the display device 100 (see FIG. 1), and at this time, the first wiring electrode 281 and the second wiring electrode 282 may be transparent electrodes. At this time, the pair electrode 261c made of a metal material may be used as a reflective layer.

[0128] For another example, the passivation layer 270 may be disposed on a rear side of the display device 100, and at this time, the dielectric layer 261b and the base portion 261a of the substrate 261 are formed of a transparent material.

[0129] Meanwhile, the semiconductor light emitting device applied to the process and device of the present

disclosure described above may be modified into various forms. Hereinafter, these modified examples will be described with reference to FIGS. 10A through 10D. FIGS. 10A through 10D are plan views showing a modified example of the semiconductor light emitting device of the present disclosure.

[0130] Referring to FIG. 10A, the center of the cross section of the first conductive semiconductor layer of the semiconductor light emitting device may be eccentrically centered on one side.

[0131] More specifically, in the semiconductor light emitting device 350, a p-type electrode 356 and an n-type electrode 352 may be spaced apart in a horizontal direction, and an n-type semiconductor layer 353 may be an egg shape which is asymmetrical with respect to one direction but symmetrical with respect to the other direction. More specifically, the shape of the n-type semiconductor layer 353 may be a conical shape with a larger length on one side thereof. In this case, the p-type electrode 356 and the n-type electrode 352 are each formed in a circular shape, and arranged in a row along the other direction. According to such a structure, the center of the cross section of the n-type semiconductor layer 353 is eccentrically formed on one side along the other direction.

[0132] For another example, referring to FIG. 10B, the semiconductor light emitting device 450 may be a symmetric structure in which an n-type semiconductor layer 453 has an elliptical shape and n-type electrodes 452 are disposed on both sides of the p-type electrode 456 therebetween.

[0133] For another example, referring to FIGS. 10C and 10D, the semiconductor light emitting device 550, 650 may be formed to have an n-type semiconductor layer 553, 653 having a polygonal shape, and have symmetrical axes equal to or less than the number of vertexes or sides thereof. In this case, n-type electrodes 552, 652 may be disposed adjacent to the respective vertexes, and the p-type electrode 556, 656 may be disposed at the center of the polygon.

[0134] The shape of the receiving groove of the wiring substrate may be set so as to match the shape of the semiconductor light emitting device described above, particularly, the shape of the n-type semiconductor layer. According to such a structure of the semiconductor light emitting device, when the semiconductor light emitting device is assembled into the receiving groove, a relative position between the n-type electrode and the p-type electrode may be always constant.

[0135] According to the process and device of the present disclosure described above, a large number of semiconductor light emitting devices may be pixelated on a wafer having a small size, and then directly transferred onto a large-area substrate. Through this, it may be possible to fabricate a large-area display device at a low cost.

Claims

1. A display device, comprising:

a semiconductor light emitting device; and
a substrate having a receiving groove in which the semiconductor light emitting device is accommodated,
wherein the semiconductor light emitting device comprises:

a first conductive semiconductor layer;
a second conductive semiconductor layer disposed at an upper portion of the first conductive semiconductor layer;
a first conductive electrode disposed on the first conductive semiconductor layer; and
a second conductive electrode disposed on the second conductive semiconductor layer, and spaced apart from the first conductive electrode along a horizontal direction, and
when the semiconductor light emitting device is assembled into the receiving groove, the first conductive semiconductor layer has an asymmetrical shape with respect to at least one direction so that the first conductive electrode and the second conductive electrode are arranged at preset positions.

2. The display device of claim 1, wherein the first conductive semiconductor layer has a symmetrical shape with respect to the other direction perpendicular to the one direction.

3. The display device of claim 2, wherein the first conductive electrode and the second conductive electrode are arranged in a row along the other direction.

4. The display device of claim 3, wherein the cross section of the first conductive semiconductor layer comprises:

a circular portion; and
a straight portion connecting both ends of the circular portion.

5. The display device of claim 3, wherein the center of the cross section of the first conductive semiconductor layer is eccentrically formed on one side along the other direction.

6. The display device of claim 1, wherein the receiving groove is formed in a passivation layer, and the receiving groove has an asymmetrical shape with respect to the one direction so as to match the shape of the first conductive semiconductor layer.

7. The display device of claim 6, wherein the first conductive electrode and the second conductive electrode are connected to a first wiring electrode and a second wiring electrode, respectively, and the first wiring electrode and the second wiring electrode are extended to one surface of the passivation layer. 5
8. The display device of claim 7, wherein the substrate comprises a plurality of pair electrodes that generate an electric field when an electric current is supplied thereto. 10
9. The display device of claim 8, wherein the first wiring electrode and the second wiring electrode are formed on an opposite side to the plurality of the pair electrodes with respect to the semiconductor light emitting devices. 15
10. The display device of claim 1, wherein at least one of the first conductive electrode and the second conductive electrode comprises a magnetic body. 20
11. A fabrication method of a display device, the method comprising: 25
- transferring a substrate to an assembly position, and placing semiconductor light emitting devices having a first conductive semiconductor layer and a second conductive semiconductor layer into a fluid chamber; 30
- guiding the movement of the semiconductor light emitting devices in the fluid chamber to assemble the semiconductor light emitting devices into receiving grooves of the substrate; and 35
- connecting a first wiring electrode and a second wiring electrode to the plurality of semiconductor light emitting devices, wherein at least one of the plurality of conductive semiconductor layers of the plurality of semiconductor light emitting devices has an asymmetrical shape with respect to one direction so that the conductive electrodes of the semiconductor light emitting devices are arranged at preset positions when the semiconductor light emitting devices are assembled into the receiving grooves. 40 45
12. The method of claim 11, wherein said assembly process comprises: 50
- applying a magnetic field to the semiconductor light emitting devices to move the semiconductor light emitting devices along a magnetic force in the fluid chamber; and 55
- guiding the semiconductor light emitting devices to the receiving grooves of the substrate by applying an electric field so that the semiconductor light emitting devices are placed at the receiving

grooves during the movement of the semiconductor light emitting devices.

FIG. 1

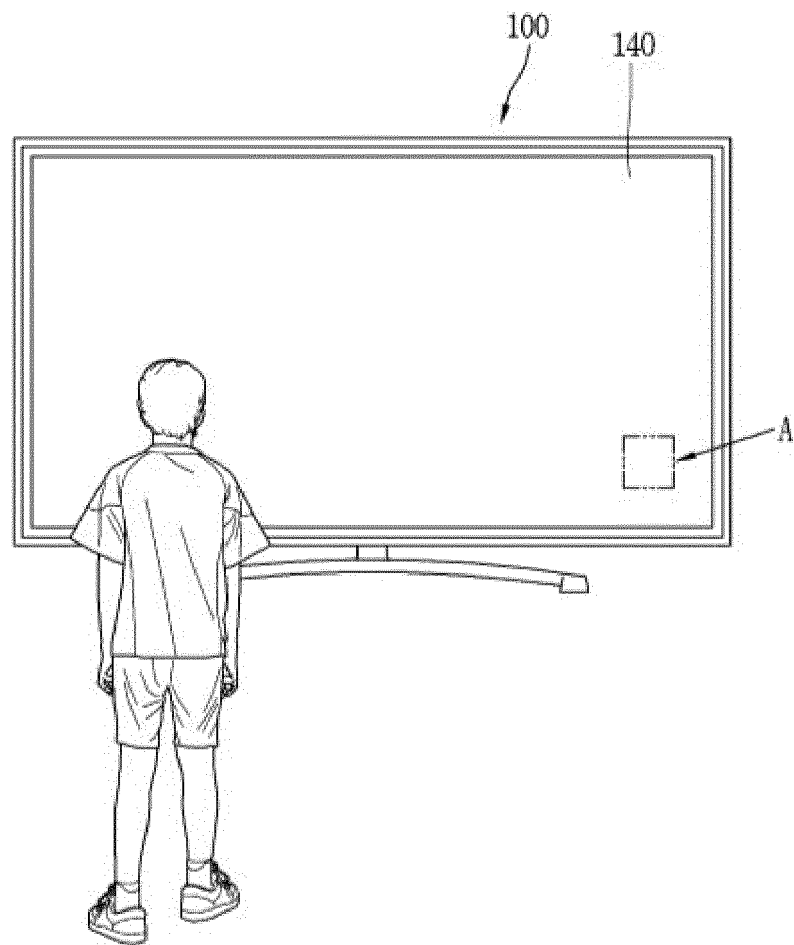


FIG. 2

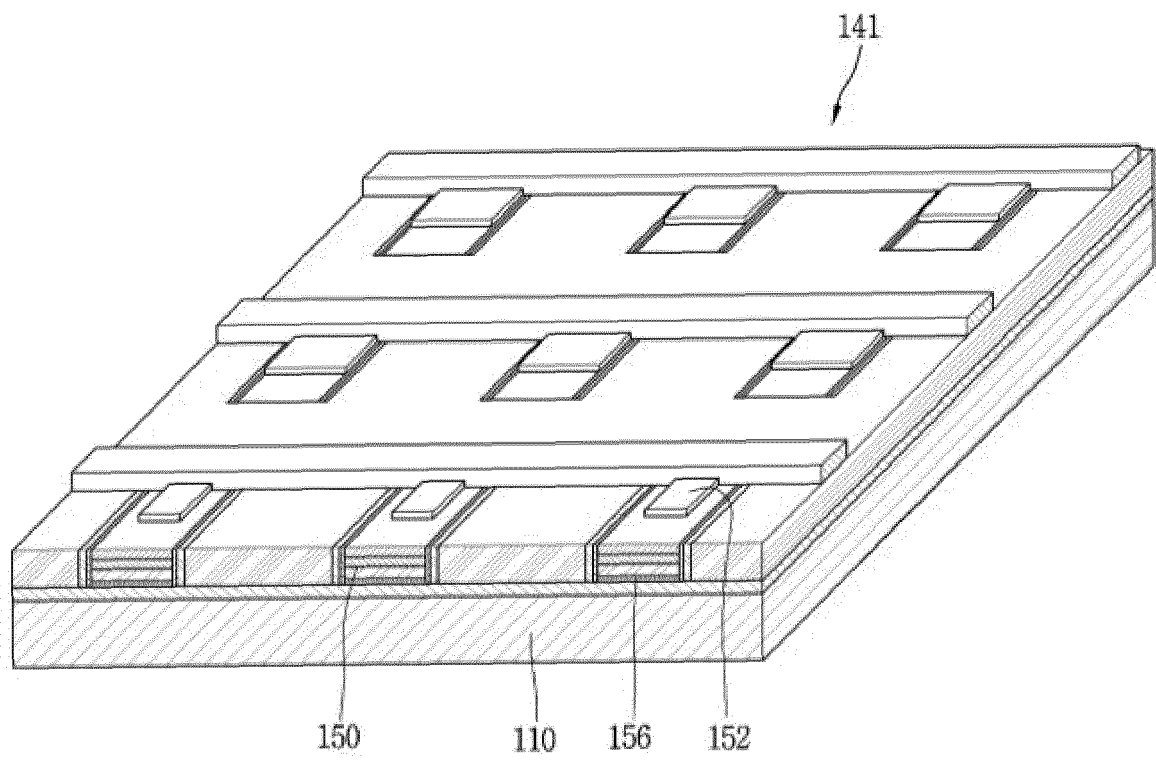


FIG. 3

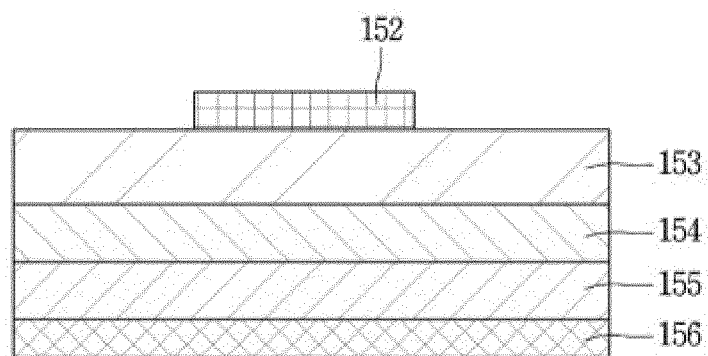


FIG. 4A

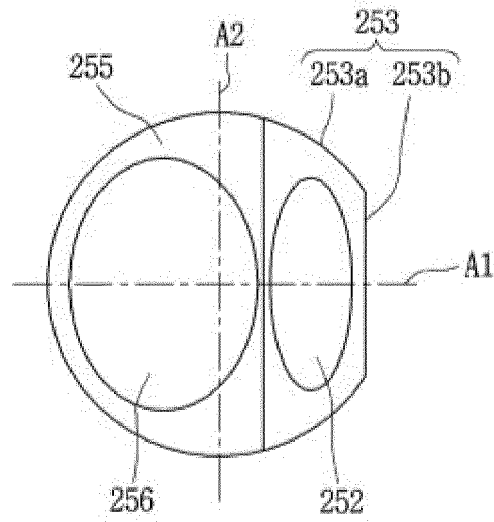


FIG. 4B

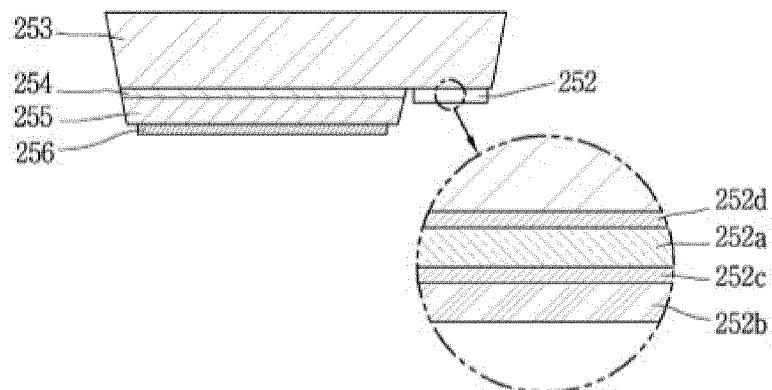


FIG. 5A

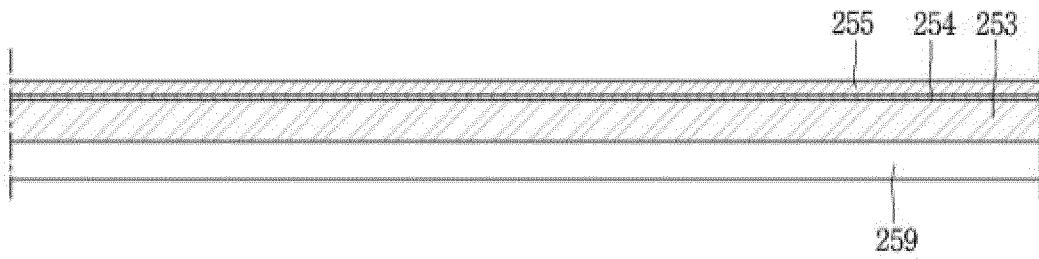


FIG. 5B

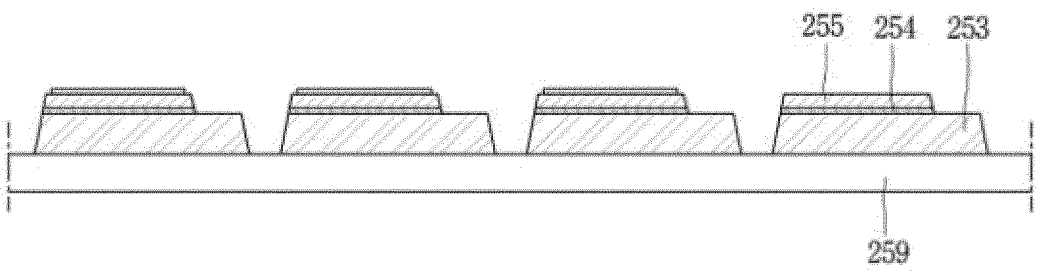


FIG. 5C

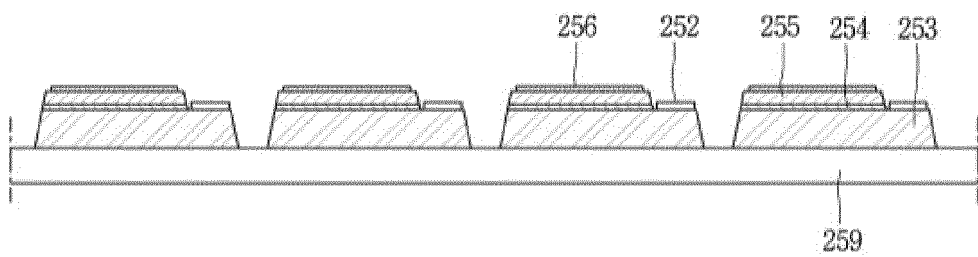


FIG. 5D

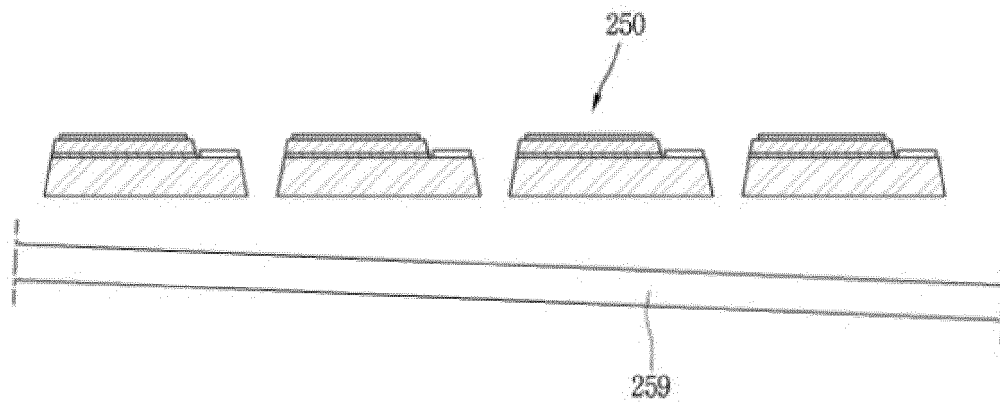


FIG. 5E

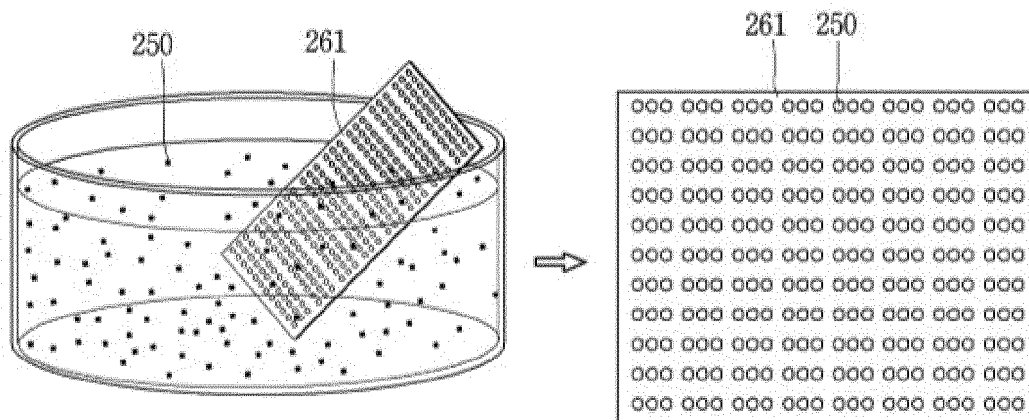


FIG. 6

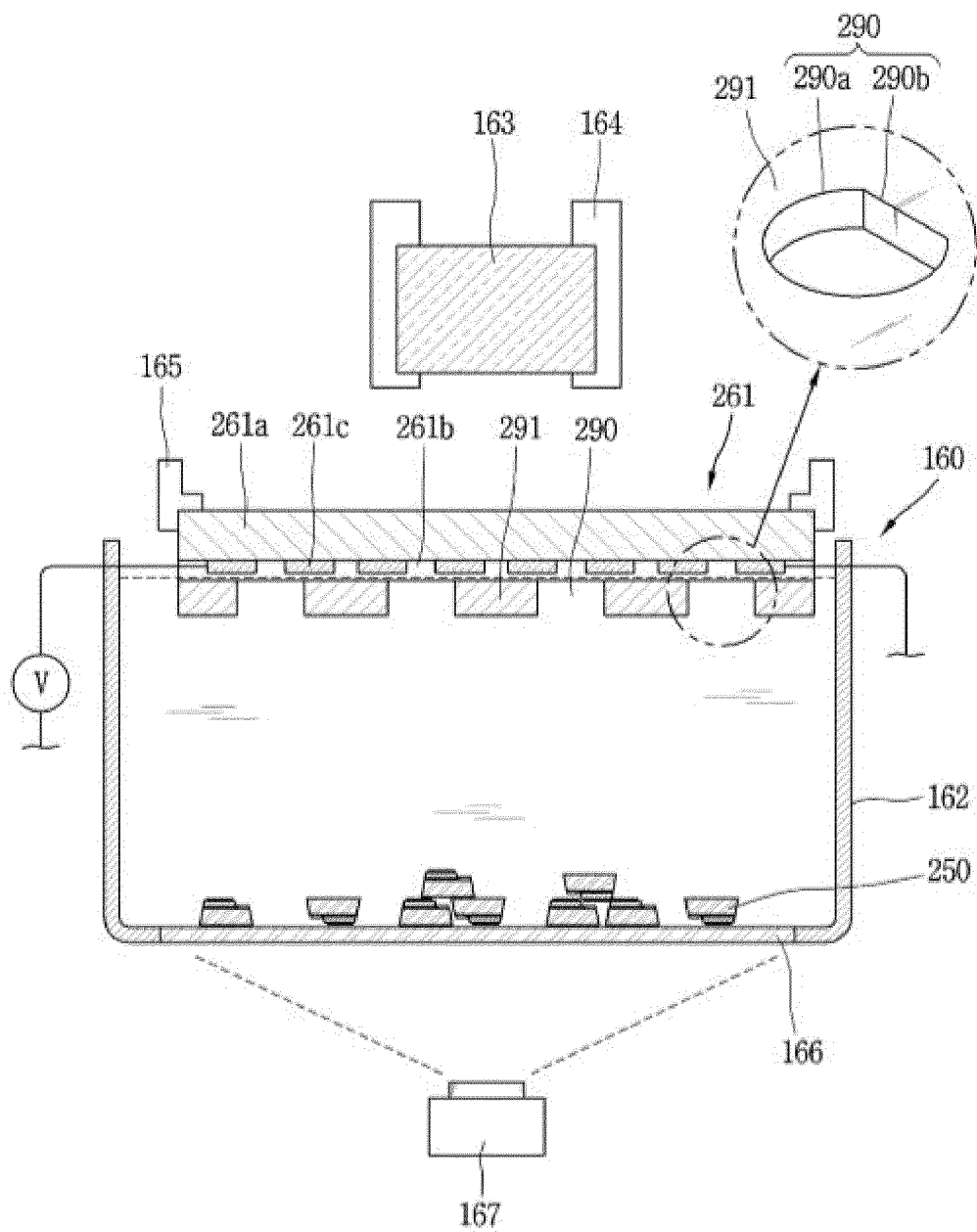


FIG. 7

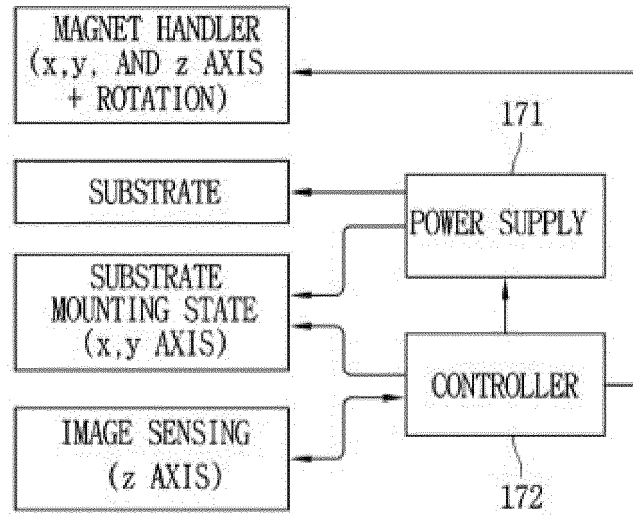


FIG. 8A

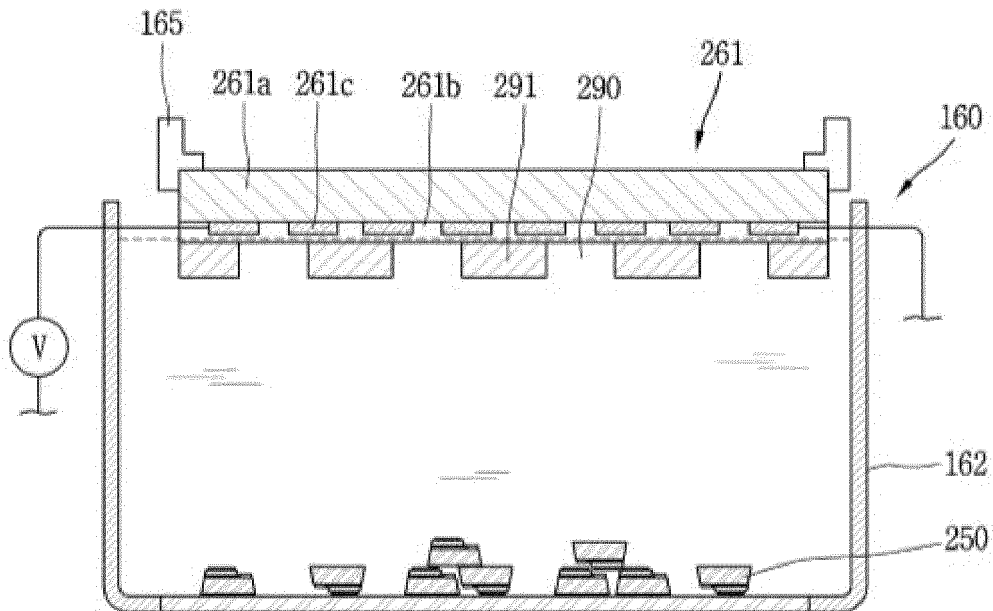


FIG. 8B

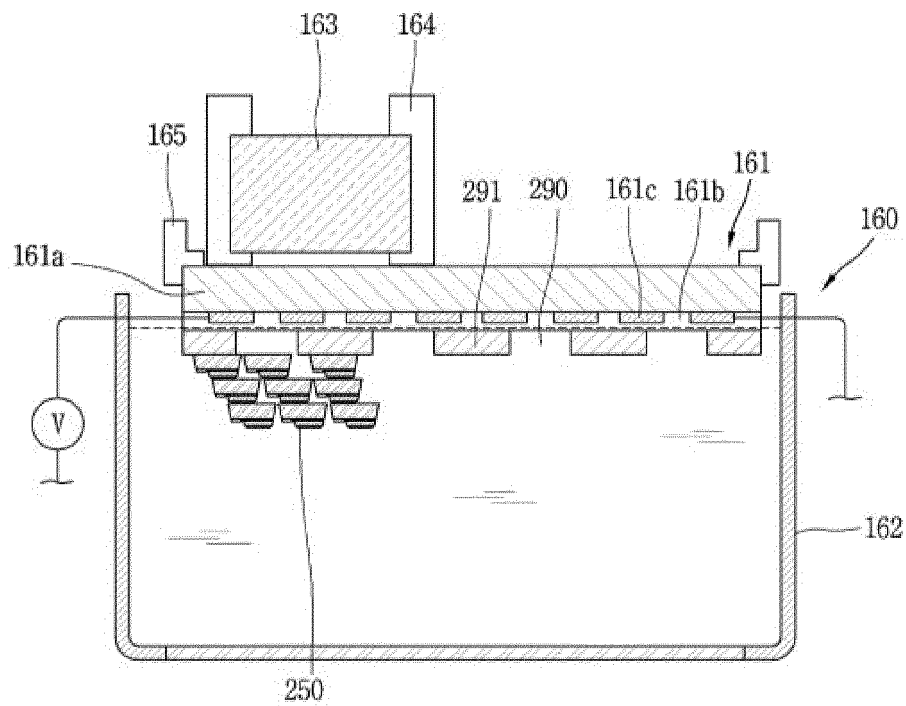


FIG. 8C

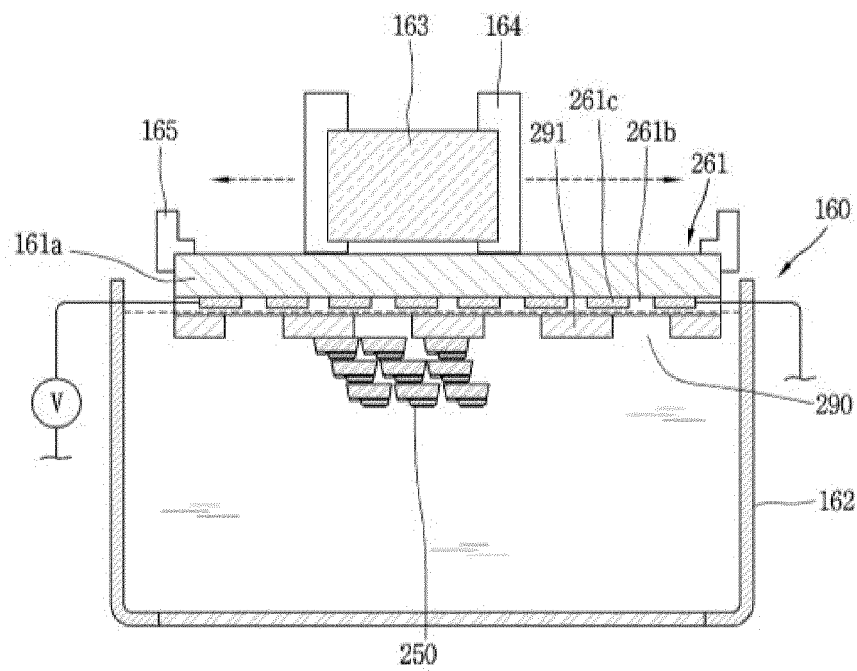


FIG. 8D

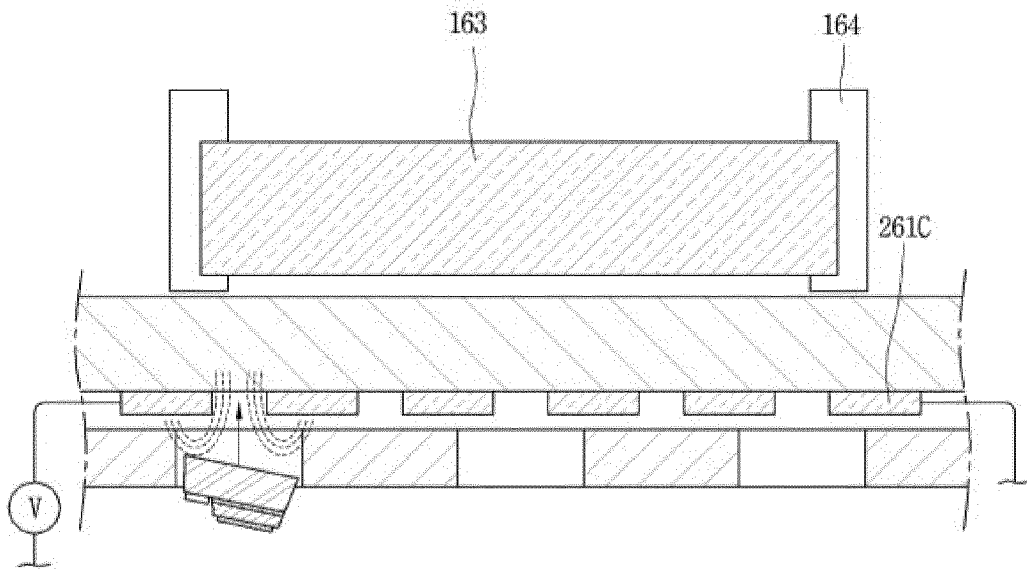


FIG. 8E

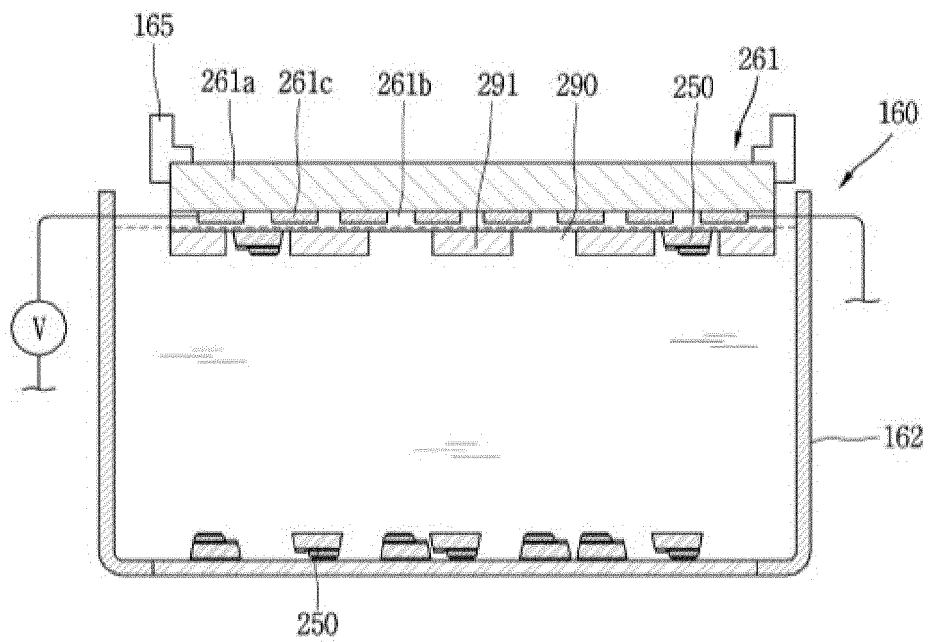


FIG. 8F

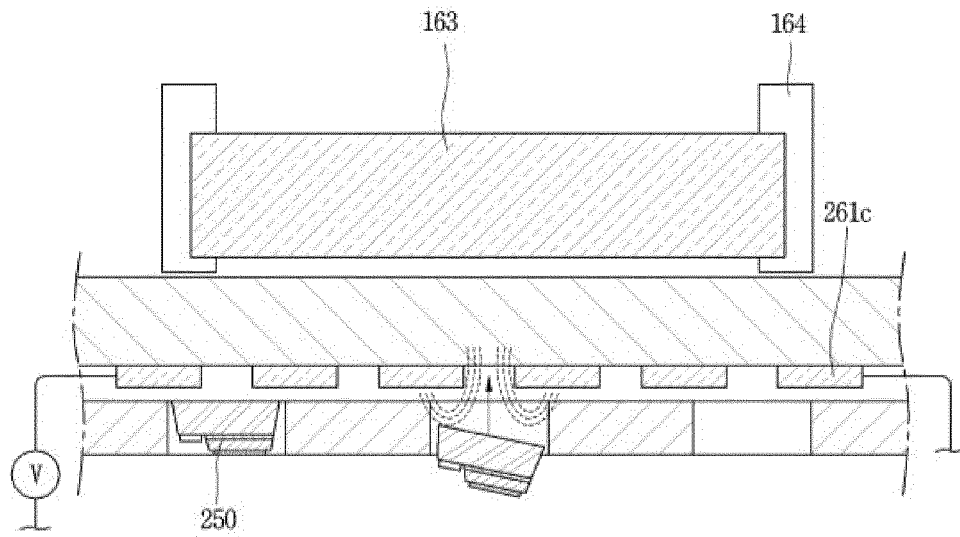


FIG. 8G

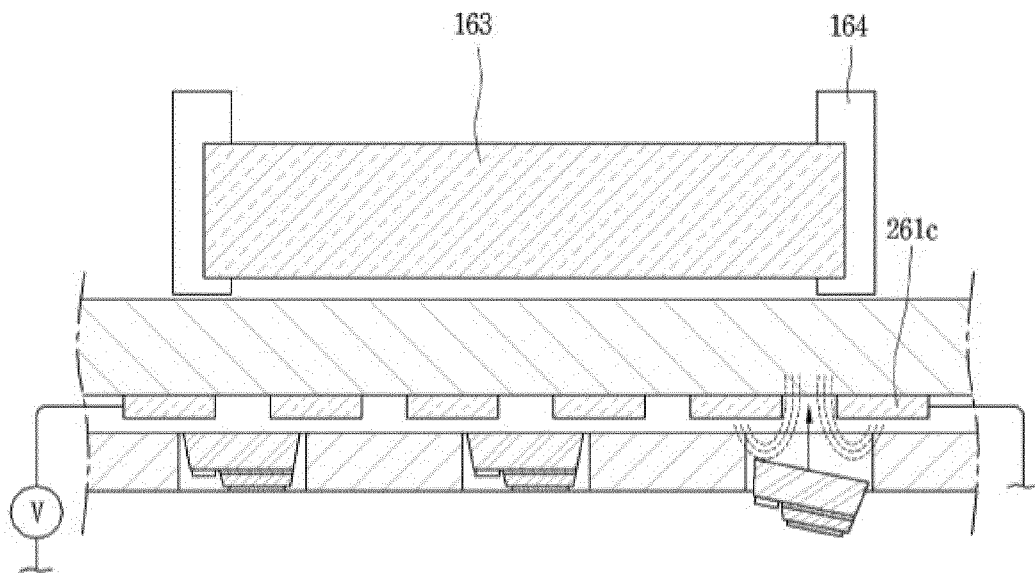


FIG. 9A

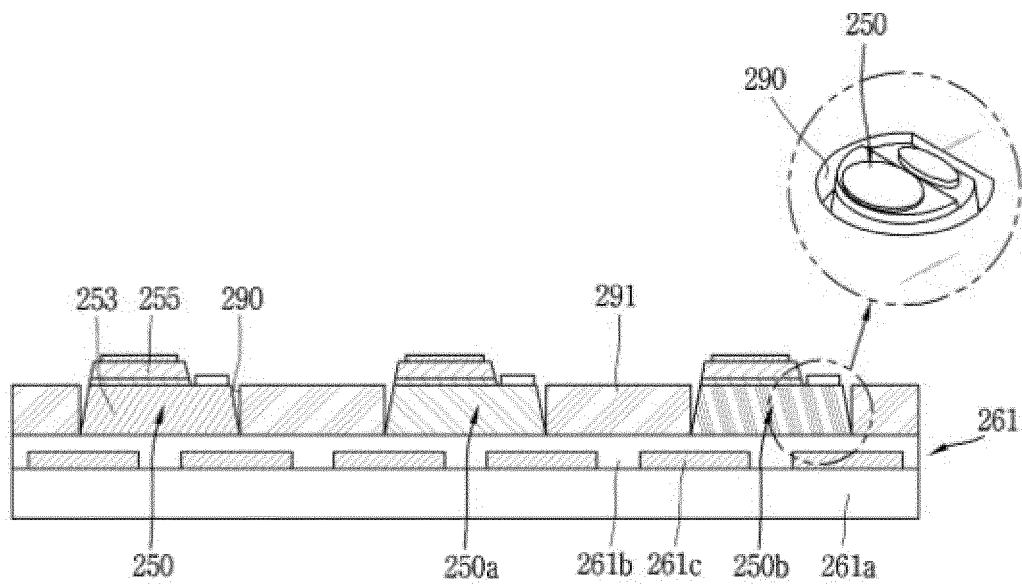


FIG. 9B

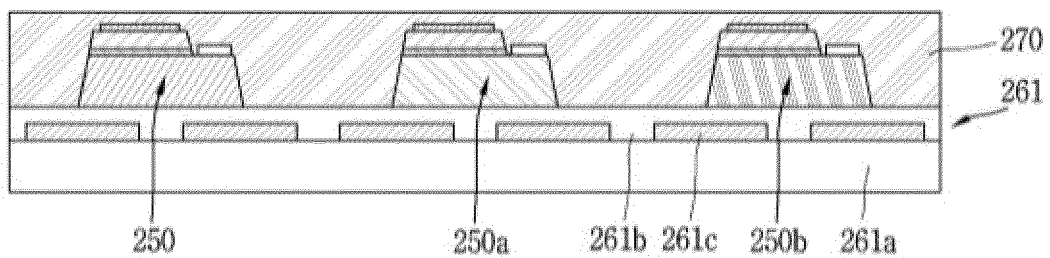


FIG. 9C

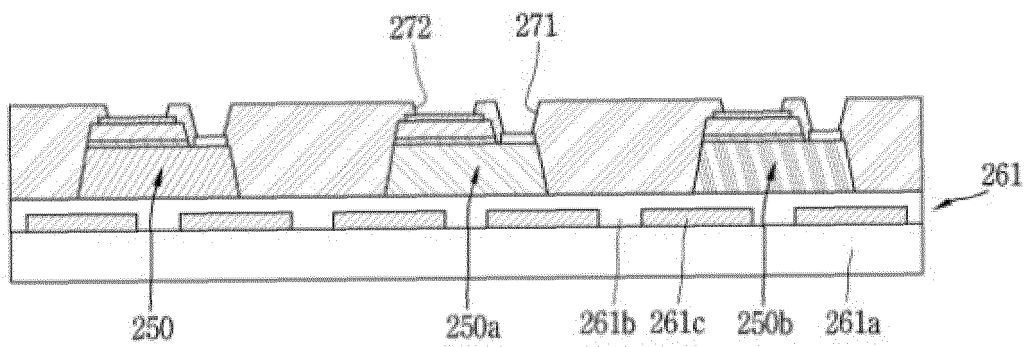


FIG. 9D

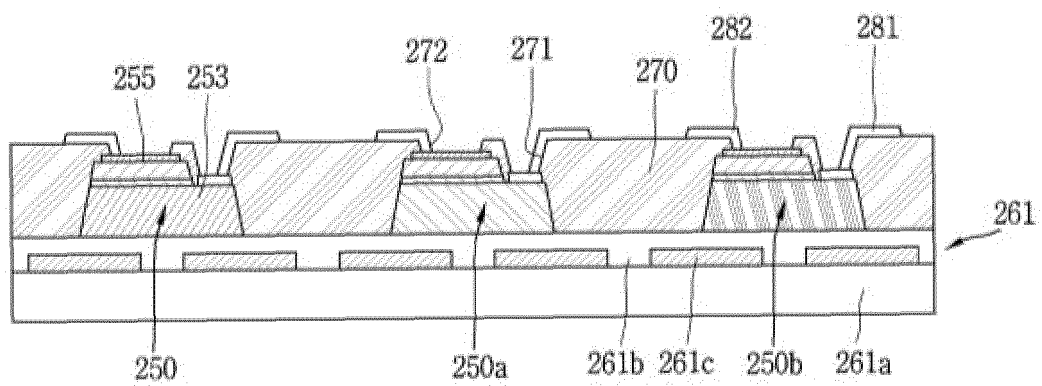


FIG. 10A

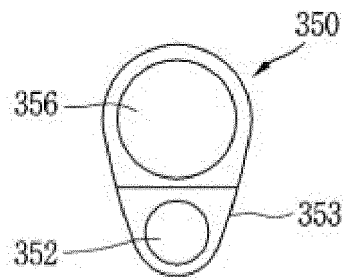


FIG. 10B

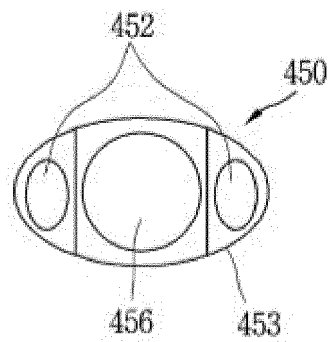


FIG. 10C

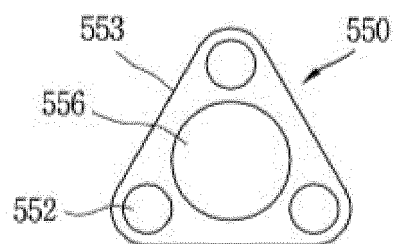
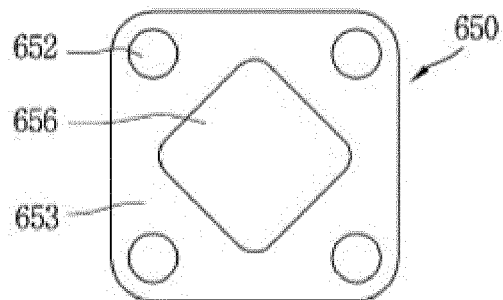


FIG. 10D



INTERNATIONAL SEARCH REPORT

International application No.

PCT/KR2018/011534

A. CLASSIFICATION OF SUBJECT MATTER

H01L 27/15(2006.01)i, H01L 33/62(2010.01)i, H01L 33/38(2010.01)i

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

H01L 27/15; H01L 21/00; H01L 23/06; H01L 33/00; H01L 33/02; H01L 33/48; H01L 33/62; H01L 33/38

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Korean utility models and applications for utility models: IPC as above

Japanese utility models and applications for utility models: IPC as above

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

eKOMPASS (KIPO internal) & Keywords: display, light emitting element, asymmetric, receiving groove, electrode, self-assembly

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	KR 10-2018-0015940 A (LG ELECTRONICS INC.) 14 February 2018 See paragraphs [0090], [0107], [0124], [0140] and figures 9, 11.	1-12
Y	US 2004-0089932 A1 (CRAIG, Gordon S.W. et al.) 13 May 2004 See paragraphs [0031], [0037].	1-12
Y	KR 10-2015-0005628 A (RENSSELAER POLYTECHNIC INSTITUTE) 14 January 2015 See paragraphs [0018], [0040].	10,12
A	US 2007-0087472 A1 (HUBER, William Hullinger et al.) 19 April 2007 See paragraphs [0013]-[0015], [0039]-[0044] and claims 1, 32.	1-12
A	KR 10-2007-0096212 A (SAMSUNG SDI CO., LTD.) 02 October 2007 See paragraphs [0025]-[0037].	1-12

☐ Further documents are listed in the continuation of Box C.
 ☒ See patent family annex.

* Special categories of cited documents:

"A" document defining the general state of the art which is not considered to be of particular relevance

"E" earlier application or patent but published on or after the international filing date

"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)

"O" document referring to an oral disclosure, use, exhibition or other means

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Date of the actual completion of the international search

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